

SPECIFICATION

产品规格书

REFOND P/N 产品型号

RF-W1SA27HS-M42

R&D 研发

Mass Product 量产供货



Contents 目录

| | |
|--|----|
| 1. Description 产品介绍 | |
| 1.1 General Description 产品描述 | |
| 1.2 Features 产品特征 | |
| 1.3 Application 产品应用 | |
| 1.4 Package Dimension 封装尺寸 | |
| 1.5 Product Parameters 产品参数 | |
| 1.6 Typical optical characteristics curves 典型光学特性曲线 | |
| 2. Packaging 产品包装 | |
| 2.1 Packaging Specification 包装规格 | |
| 2.1.1 Carrier Tape Dimension 载带尺寸 | 11 |
| 2.1.2 Reel Dimension 卷盘尺寸 | 11 |
| 2.1.3 Label Form Specification 标签规格 | 12 |
| 2.2 Moisture Resistant Packing 防潮包装 | |
| 2.3 Cardboard Box 包装纸箱 | |
| 2.4 Reliability Test Items And Conditions 信赖性测试项目及条件 | |
| 2.5 Criteria For Judging Damage 失效判定标准 | |
| 3. SMT Reflow Soldering Instructions SMT 回流焊说明 | |
| 3.1 SMT Reflow Soldering Instructions SMT 回流焊说明 | |
| 3.1.1 Soldering Iron 烙铁焊接 | 17 |
| 3.1.2 Repairing 修补 | 17 |
| 3.1.3 Cleaning 清洗 | 17 |
| 4. Handling Precautions 产品使用注意事项 | |
| 4.1 Handling Precautions 产品使用注意事项 | |
| 4.1.1 Storage 贮存 | 18 |
| 4.1.2 Static Electricity 静电 | 19 |
| 4.1.3 Reverse voltage protection 反压保护 | 19 |
| 4.1.4 The safe temperature for LEDs working 温度保护 | 19 |

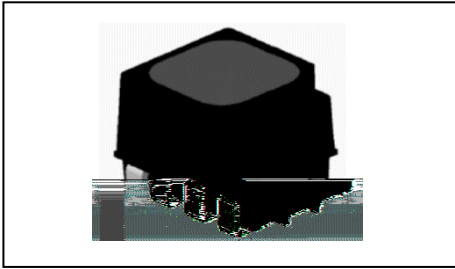


| | |
|-----------------------------------|----|
| 4.1.5 Directionsfor Use 使用指南..... | 20 |
| 4.1.6 Others 其它事项 | 22 |
| 4.1.7 Declare 申明..... | 23 |



1. Description 产品介绍

1.1 General Description 产品描述



The product is a full-color LED device, High contrast(Designed on all black surface). The product size: 2.8mmx2.7mmx2.45mm.

该产品为全彩 LED 器件，高对比度(全黑外观设计)，产品尺寸: 2.8mmx2.7mmx2.45mm。

1.2 Features 产品特征

Extremely wide viewing angle. 发光角度大

High luminous Intensity, Low power dissipation, Good reliability and Long life.

光强高、功耗低、可靠性好、寿命长

Water-resistant (IPX6). 防水等级(IPX6)

Moisture sensitivity level: 5a. 潮湿敏感等级:5a

RoHS compliant. 满足RoHS要求

Matte surface. 哑光表面

Pb-free reflow soldering application. 无铅回流焊

1.3 Application 产品应用

Outdoor full-color video screen. 户外全彩显示屏

Indoor and outdoor decorative lighting. 室内外装饰照明

Amusement. 娱乐产品

General use. 其他应用



1.4 Package Dimension 封装尺寸

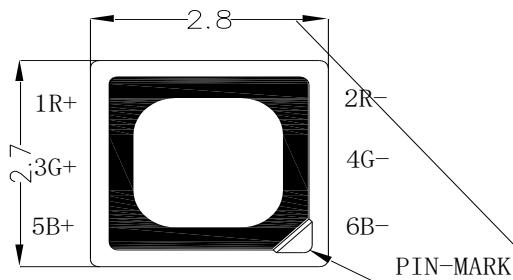


Fig. 1-1 Top view 正面视图

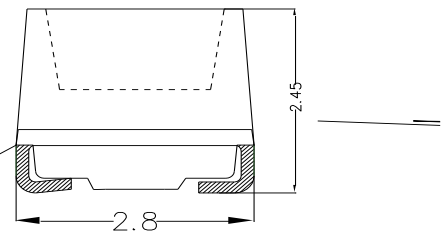


Fig. 1-2 Side view 侧面视图

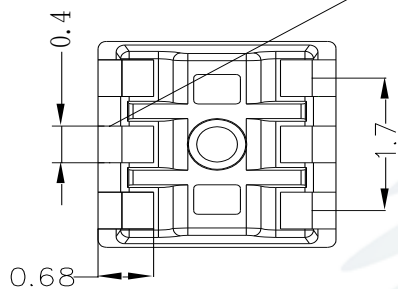


Fig. 1-3 Bottom view 背面视图

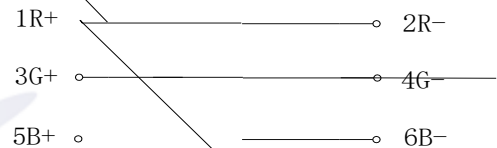


Fig. 1-4 Polarity 极性

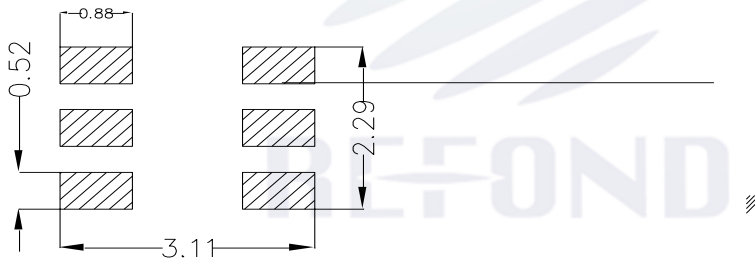


Fig. 1-5 Soldering patterns 推荐焊盘

Fig. 1-6 Glue filling 灌胶

Notes 备注:

1. All dimensions units are millimeters. 所有尺寸标注单位为毫米
2. All dimensions tolerances are ± 0.1 mm unless otherwise noted. 除特别标注外, 所有尺寸公差为 ± 0.1 毫米
3. Recommendation for glue filling: filling height must be higher than or equal to 1.0 mm. 灌胶建议: 灌胶高度必须大于等于 1.0 mm



1.5 Product Parameters 产品参数

Table 1-1 Electrical / Optical Characteristics at Ts=25°C 电性与光学特性

| Item 项目 | Symbol 符号 | Test Condition 测试条件 | Value | | | Unit 单位 |
|--|----------------------|--|-------------|-------------|-------------|---------|
| | | | R | G | B | |
| Reverse Current (反向电流) | I _R | V _R =5V | 6 | 6 | 6 | |
| Forward Voltage (正向电压) | V _{F (min)} | R I _F = 20mA G I _F = 20mA B I _F = 20mA | 1.7 | 2.5 | 2.5 | V |
| | V _{F (max)} | | 2.4 | 3.3 | 3.3 | V |
| Dominant Wavelength 主波长 | λ _D | | 617~ 628 | 520~545 | 460~475 | nm |
| | | | 5nm per Bin | 3nm per Bin | 3nm per Bin | |
| Spectrum Radiation Bandwidth 半波宽 | | | 24 | 38 | 30 | nm |
| Luminous Intensity 发光强度 | I _{V(min)} | | 365 | 640 | 120 | mcd |
| | I _{V(avg)} | | 550 | 960 | 185 | mcd |
| | I _{V(max)} | | 825 | 1440 | 278 | mcd |
| | BIN Range | | 1:1.3 | 1:1.3 | 1:1.3 | |
| Viewing Angle (发光角度) | % 1/2 | | | 110 | | |

Table 1-2 Absolute Maximum Ratings at Ts=25°C 最大额定参数

| Parameter (参数) | Symbol (符号) | Absolute Maximum Ratings (最大额定参数) | | | Unit 单位 |
|---------------------------------------|------------------|--------------------------------------|-----|-----|---------|
| | | R | G | B | |
| Forward Current (正向电流) | I _F | 25 | 20 | 20 | mA |
| Reverse Voltage (反向电压) | V _R | 5 | 5 | 5 | V |
| Operating Temperature (工作温度) | T _{OPR} | -30 ~ +85 | | | °C |
| Storage Temperature (储存温度) | T _{STQ} | -40 ~ +100 | | | °C |
| Power Dissipation (功率) | P _D | 60 | 68 | 68 | mW |
| Total Junction Temperature (结温) | T _J | 115 | 115 | 115 | °C |
| Electrostatic Discharge (HBM) (静电) | E _{SD} | 1000V | | | |

Notes 备注:

1. The above forward voltage measurement allowance tolerance is $\pm 0.1V$. 上述电压的测试公差范围 $\pm 0.1V$ 。
2. The above Tolerance of measurement of dominant wavelength $\pm 1nm$. 上述波长的测试公差范围 $\pm 1nm$ 。
3. The above luminous intensity measurement allowance tolerance $\pm 10\%$. 上述发光强度的测试公差范围 $\pm 10\%$ 。
4. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product. 使用功率不能超过规定的最大额定值。
5. All measurements were made under the standardized environment of Refond. 所有测试都是基于瑞丰现有的标准测试平台。
6. Luminous intensity range is for reference only,specific parameters please refer to the label. 发光强度范围仅供参考,请以实物标签为准。

1.6 Typical optical characteristics curves 典型光学特性曲线

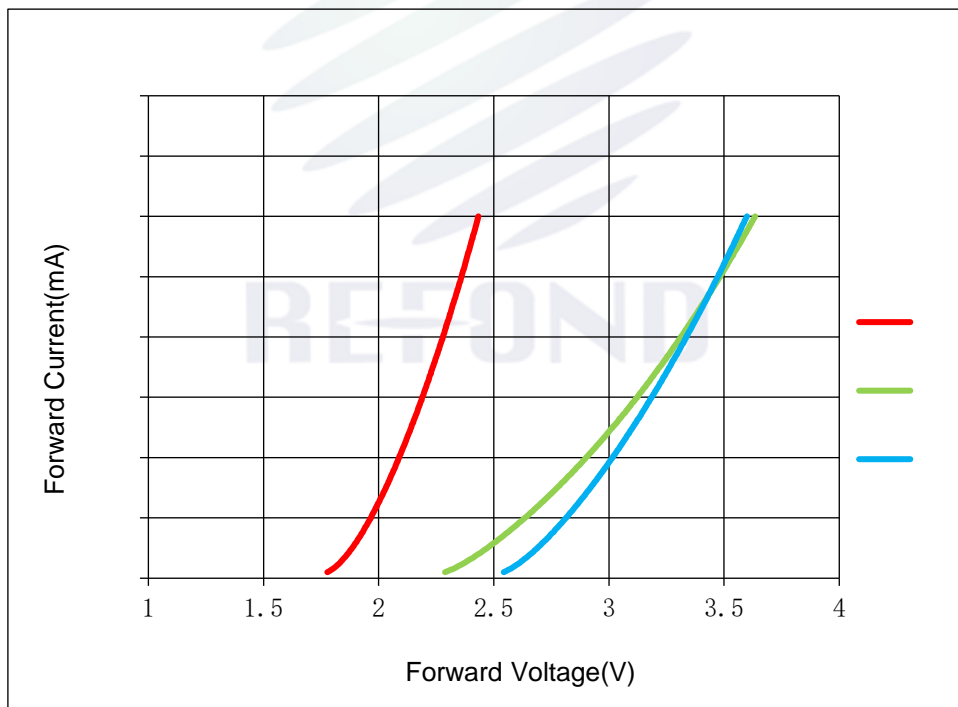


Fig 1-6 Forward Voltage Vs. Forward Current 伏安特性曲线



Fig 1-7



Fig 1-9 Solder Temperature Vs Forward Current 引脚温度与正向电流特性曲线

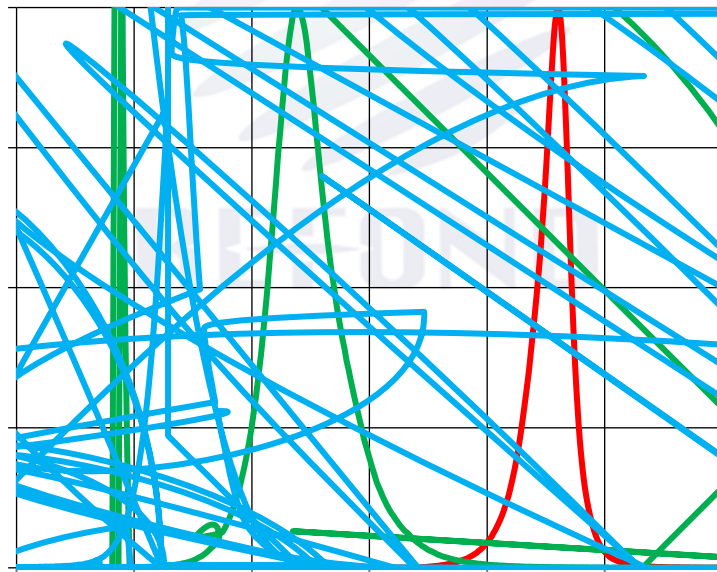


Fig 1-10 Spectrum Distribution 光谱分布特性曲线



Fig 1-11 Directivity X-X radiation angle X轴方向辐射角度

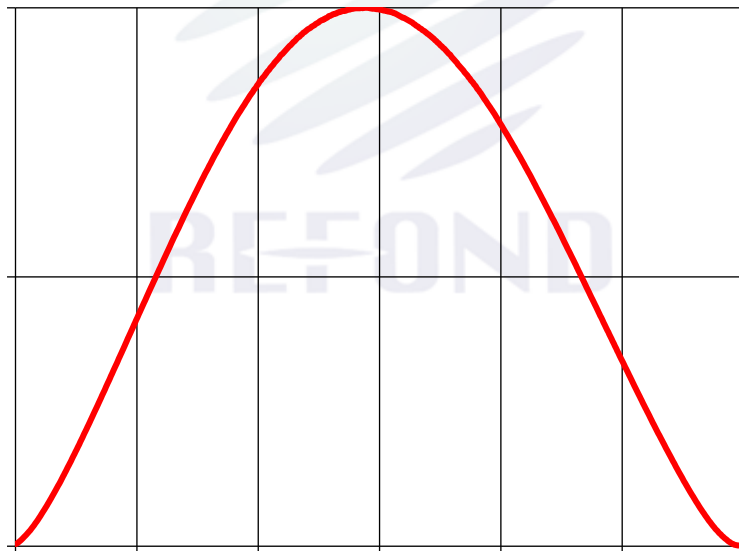


Fig 1-12 Directivity Y-Y radiation angle Y轴方向辐射角度



2. Packaging 产品包装

2.1 Packaging Specification 包装规格

Package:10000pcs/reel.包装每卷 10000pcs。

2.1.1 Carrier Tape Dimension 载带尺寸

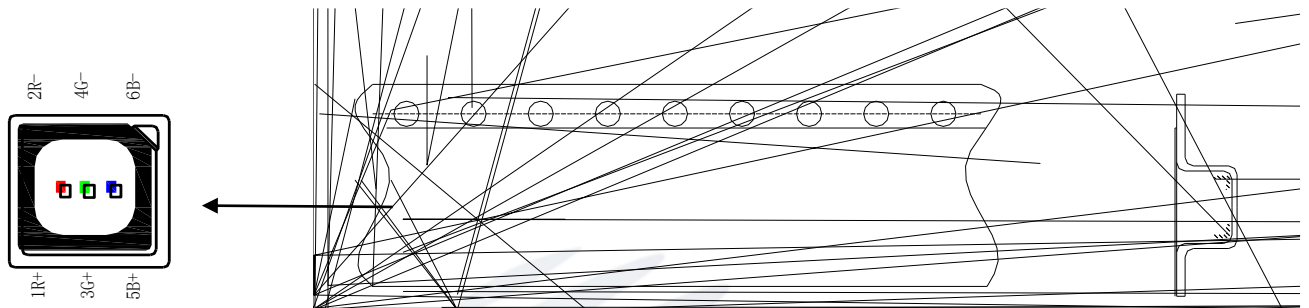


Fig.2-1 Carrier Tape Dimension 载带尺寸

2.1.2 Reel Dimension 卷盘尺寸

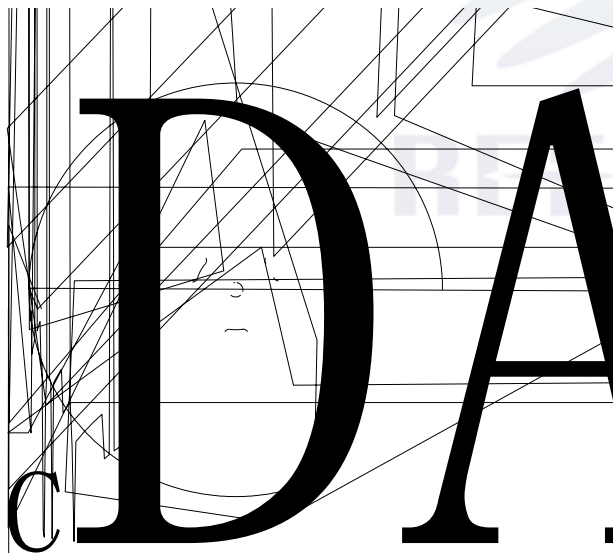


Fig.2-2 Reel 卷盘

Table 2-1 Dimension 描述

| | |
|---|-------------------|
| A | 400±2mm |
| B | 100.0±0.4mm |
| C | 14.3±0.3mm |
| D | 2.6±0.2mm |
| E | 12.4±0.3mm |
| F | 8.6 + 0.2/-0.3 mm |
| T | 1.9±0.2mm |

Notes 备注:

The tolerances unless mentioned ±0.1mm. Unit : mm 注: 未注公差为±0.1毫米, 尺寸单位为毫米。





2.3 Cardboard Box 包装纸箱

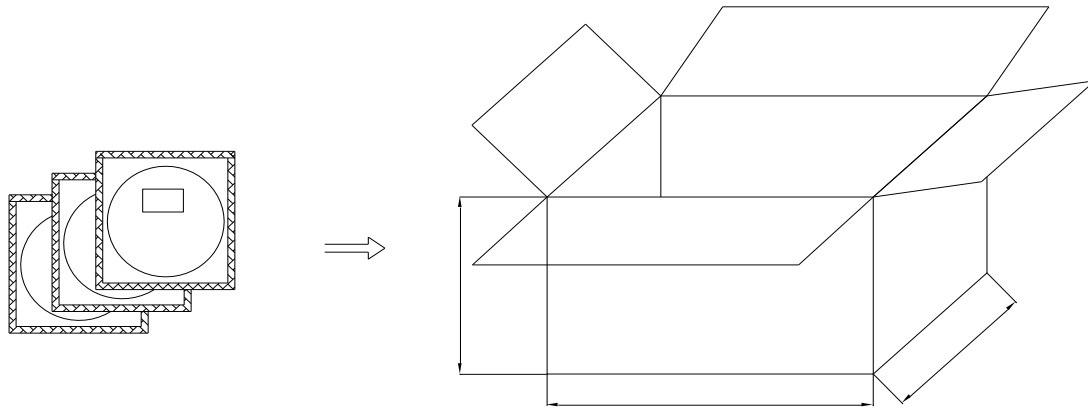


Fig.2-5 Box 包装箱

2.4 Reliability Test Items And Conditions 信赖性测试项目及条件

Table 2-3 Reliability Condition 可靠性条件

| Test Items 项目 | Ref.Standard 参考标准 | Test Condition 测试条件 | Time 时间 | Quantity 数量 | Ac/Re 接收/拒收 |
|--------------------------------------|---------------------------|--|------------|----------------|----------------|
| Resistance to Soldering Heat 耐焊接热 | JESD22-B106 | Temp:260°Cmax T=10 sec | 3times | 22pcs. | 0/1 |
| Thermal Shock 冷热冲击 | JEITAED-4701 300 307 | -40°C 15min 10s 100°C 15min | 500cycle | 22pcs. | 0/1 |
| Moisture Resistance 防潮性 | IPC/JEDEC J-STD-020D.1 | 1. Moisture Absorption Ta=85°C/ RH=85%/12HR 2. Tsol=260°C, T=10s Reflow Soldering | 3times | 22pcs. | 0/1 |
| High Temperature Storage 高温保存 | JEITAED-4701 200 201 | Temp:100°C | 1000hrs. | 22pcs. | 0/1 |



| | | | | | |
|---|--------------------------|--|----------|--------|-----|
| Low Temperature Storage 低温保存 | JEITA ED-4701 200 202 | Temp:-40°C | 1000hrs. | 22pcs. | 0/1 |
| Room Temperature Operating Life 常温寿命测试 | JESD22-A108 | T _A =25°C I _F =20mA | 1000hrs. | 22pcs. | 0/1 |
| High Temperature High Humidity Life Test 高温高湿寿命测试 | JESD22-A101 | 85°C/ 85%RH I _F =10mA | 500hrs. | 22pcs. | 0/1 |
| Temperature Humidity Storage 高温高湿储存 | JEITA ED-4701 100 103 | T _A =85°C R _H =85% | 1000hrs. | 22pcs. | 0/1 |
| Low Temperature Life Test 低温寿命 | JESD22-A108D | T _A =-40°C, I _F =20mA | 1000hrs. | 22pcs. | 0/1 |

2.5 Criteria For Judging Damage 失效判定标准

Table 2-4 Criteria 标准

| Test Items 项目 | Symbol 符号 | Test Condition 测试条件 | Criteria For Judgement 判定标准 |
|---------------------------|----------------|------------------------|---|
| Forward Voltage 正向电压 | V _F | I _F =20mA | Initial Data ±10% 初始值 ±10% |
| Reverse Current 反向电流 | I _R | V _R = 5V | I _R |
| Luminous Intensity 光强 | I _v | I _F =20mA | Average I _v degradation rate 平均 I _v 衰减 ≤30% |
| Material appearance 外观 | / | / | No internal cracks, no material between stripped, no deaded light 材料无内部裂痕、无剥离、无死灯 |

Notes 备注:

1. The Reliability tests are based on Refond existing test platform. 可靠性测试基于瑞丰现有的测试标准。
2. The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform, the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit,

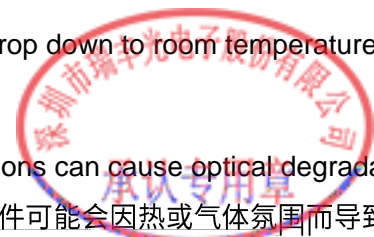


Table 3-1 Description 描述

| | |
|---|----------------------|
| Average temperature rise speed平均升温速度 (T _{max} 至T _P) | Max 4 °C/ s 最高4 °C/秒 |
| Preheating: minimum temperature预热: 最低温度 (T _{min}) | 150 °C |
| Preheating: Max temperature预热: 最高温度 (T _{max}) | 200 °C |
| Preheating: Time预热: 时间 (T _{min} 至T _{max}) | 60s-120s 60 - 120秒 |
| Time limited to maintain high temperature: the temperature 限时维持高温: 温度 (T _L) | 217 °C |
| Time limited to maintain high temperature: The Time 限时维持高温: 时间 (t _L) | Max 60s 最多60秒 |
| Peak /Classification of temperature: 峰值 / 分类温度 (T _P) | 245 °C |
| Time limit classification of peak temperature time 限时峰值分类温度: 时间 (t _p) | Max 10s 最多10秒 |
| Hold time within 5 °C with the actual peak temperature (T _P) 与实际峰值温度 (T _P) 相差 5 °C 以内的保持时间 | Max 30s 最多30秒 |
| Cooling speed 降温速度 | Max 6 °C/ s 最高6 °C/秒 |
| Needed time from 25 °C to T _p 25 °C 升至峰值温度所需时间 | Max 8 minutes 最多8分钟 |

Notes 备注:

- 1.Reflow soldering should not be done more than one times.回流焊接最多只能进行一次。
- 2.It is recommended that use the middle temperature solder paste.推荐使用中温锡膏生产加工。
- 3.Stress on the LEDES should be avoided during heating in soldering process.在回流焊接过程中,不要对 LED 施加任何压力。
- 4.After soldering ,do not deal with the product before its temperature drop down to room temperature.在焊接完成后,待产品温度下降到室温后,再进行其它处理。
5. Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat or atmosphere. 建议使用氮气回流焊, 在空气中焊接条件可能会因热或气体氛围而导致光学性能。



下降.

6. This product can differ in optical characteristics depending on the number of reflow cycles. In a single display, only LEDs with same number of reflow cycles should be used regardless of the application type, such as rental and/or permanent installations. 本产品的光学特性可能会因回流循环次数而导 在单个显示屏中, 无论使用哪种安装, 都应仅使用回流次数相同的类型 (例如租赁或永久LED).

7. This LED is designed to be reflow soldered on to a PCB. If dip soldered, cannot guarantee its reliability. 此LED设计为回流焊接到PCB上, 如果采用浸焊, 无法保证其可靠性.

3.1.1 Soldering Iron 烙铁焊接

(1) When hand soldering, keep the temperature of iron below less 300°C less than 3 seconds 当手工焊接时, 烙铁的温度必须小于300°C, 时间不可超过3秒。

(2) The hand solder should be done only one time. 手工焊接只可焊接一次。

3.1.2 Repairing 修补

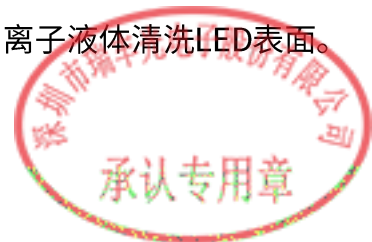
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

LED回流焊后不应该修复, 当必须修复时, 必须使用双头烙铁, 而且事先应确认此种方式会不会损坏LED本身的特性。

3.1.3 Cleaning 清洗

The LEDs should not be cleaned with water, benzene, and/or thinner. Alcohol is recommended for cleaning. Before cleaning with other similar solvents, please make sure that the solvent used will not cause damage to the LED. Do not use ionic liquids containing "Cl" and "S" elements to clean the LED surface.

不应用水、苯和/或稀释剂清洗led。推荐使用酒精进行清洗, 使用其它类似溶剂清洗前, 请先确认使用的溶剂不会对LED造成损伤. 不要使用含有“Cl” “S”元素的离子液体清洗LED表面。



4.Handling Precautions 产品使用注意事项

4.1 Handling Precautions

4.1.1 Storage 贮存

(1) Moisture proof and anti-electrostatic package with moisture absorbent material is used, Suggest storage time is less than 6 months.

本产品使用密封防潮抗静电袋包装,并附有干燥剂, 储存时间不要超过6个月。

(2) Storage condition: temperature $\leq 30^{\circ}\text{C}$, humidity $\leq 60\% \text{ RH}$.

开封前, 产品必须储存在温度 $\leq 30^{\circ}\text{C}$ 、相对湿度 $\leq 60\%$ 的环境里。

(3) Before opening the package, please check the package for air leaks, if there exists any air leaks, please return the product to our company for package after dehumidification by baking before your second use.

在开包装之前, 请先检查包装袋有无漏气, 如果有漏气现象, 请退回我司重新烘烤除湿包装后再使用。

(4) After the package is opened, the product must be used in the specified environment of temperature below 30°C /humidity below 60% RH, and soldered within 12HR. Unused material must be stored in the environment of temperature below 30°C /humidity below 10% RH, These surplus products should be baked $65 \pm 5^{\circ}\text{C}/24\text{H}$ before next use.

包装袋开启后,产品必须: 在规定环境温度 30°C 以内、湿度60%RH以下的条件中使用; 并且需要在12小时内焊接完毕; 未使用完的材料需存储在温度 30°C 以内, 湿度:10%RH以内的环境中, 下次使用前需烘烤使用, 烘烤条件: $65 \pm 5^{\circ}\text{C}/24\text{H}$ 。

(5) Before SMT, LEDs need to be baked, baking requirement as below: 上线贴片前, 必须对产品进行烘烤除湿, 烘烤条件如下:

| Customer pre-treatment conditions before use 客户使用前处理方式 | | | | |
|--|---|---|---|---|
| Condition before use 使用前情况: | undamped, Production date: 2 months 未受潮, 生产日期2个月以内 | undamped, Production date: 2-6 months 未受潮, 生产日期为2-6个月 | undamped, Production date: 6-12 months 未受潮, 生产日期为6-12个月 | damped, or Production date: exceed 12 months 已受潮, 或生产日期超过12个月 |
| Pre-treatment 处理方式: | Baked $65^{\circ}\text{C} \pm 5^{\circ}\text{C}/12\text{H}$ 烘烤 $65^{\circ}\text{C} \pm 5^{\circ}\text{C}/12\text{H}$ | Baked $65^{\circ}\text{C} \pm 5^{\circ}\text{C}/24\text{H}$ 烘烤 $65^{\circ}\text{C} \pm 5^{\circ}\text{C}/24\text{H}$ | Baked $65^{\circ}\text{C} \pm 5^{\circ}\text{C}/48\text{H}$ 烘烤 $65^{\circ}\text{C} \pm 5^{\circ}\text{C}/48\text{H}$ | Return to the original factory for processing 退回原厂处理 |

4.1.2 Static Electricity 静电

Static electricity and surge voltage damage the LEDs. Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs do not light at the low current and even not light. All devices, equipment and machinery must be properly grounded. At the same time, it is also recommended that anti-electrostatic wrist bands, pads, uniforms, gloves or containers can be used as effective measures when dealing with the LEDs.

静电和电涌会导致产品特性发生改变,例如正向电压降低等,如果情况严重甚至会损毁产品。所以在使用时必须采取有效的防静电措施。所有相关的设备和机器都应该正确接地,同时必须采取其他防止静电和电涌的措施。使用防静电手环,防静电垫子,防静电工作服、工作鞋、手套,防静电容器,都是有效的防止静电和电涌的措施。

4.1.3 Reverse voltage protection 反压保护

In generally the reverse current of LED is very small, it can't effect using the component normally, but when it often suffered the reverse voltage which exceed the limits of the component than it will be damaged, the reverse current increases rapidly causing the string light display gray scale so when designing, please pay attention to control the reverse voltage we suggest the reverse voltage less than 5V.

通常 LED 的反向漏电流都会很小,不会影响正常使用。如果长期遭受超过其所能承受的反向电压冲击时,LED 会损伤,反向漏电流会迅速变大,引起显示屏零灰度下串光的发生。在设计中,要注意控制反向电压,建议加在 LED 上的反向电压值不超过 5V。

4.1.4 The safe temperature for LEDs working 温度保护

(1) G X Z gX cXeTgheX T X g X 87 f Luminous Intensity deceased radically, if LEDs worked in hot environment for a long time, they will be disabled easily. When LEDs are working in T Vbf XWTæT XfhZZXf gg Tgg X 87 f surface temperature should be lower than 55°C and the XZf temperature should be lower than 75°C.

LED 在高温条件下,衰减会加速,寿命也会缩短,若长期处于高温环境下,极容易出现失效。对于高密度排列使用的情况,建议在使用过程中灯面温度不超过 55°C,灯脚温度不超过 75°C。

(2) Proper thermal management is an important when designing products with LEDs. LED die temperature is affected by PCB thermal resistance and LED spacing on the board. Please design



在矩阵驱动的 LED 上备用时，请确保反向电压不超过绝对最大额定值，确保不要将过大的电压（例如雷电）施加到 LED 上。

(6) Aging is recommended in order to detect manufacturing and assembly defects. Particularly, make sure that excessive current and/or voltage is not applied to the LEDs. This aging should be conducted in environments where water condensation does not occur.

建议进行老化以检测制造和组装缺陷；特别要确保没有对 LED 施加过大的电流或电压。该老化应在不发生水凝结的环境中进行。

(7) when the LEDs are used in the following environments, incorporate sufficient measures into the display to prevent debris, water/moisture and gases that will adversely affect the product.

- where water vapor is abundant
- where water condensation is likely to occur
- where water is likely to splash onto the LEDs
- where frost is likely to form on the surface of the LEDs (e.g. freezer, ice skating rink, etc.)
- where dust, dirt, debris, loose metallic materials and/or gases that will adversely affect the product are present

在以下环境中使用LED时，请在显示屏中采取足够的措施，以防止会对产品产生不利影响的碎屑、水及气态。

- 水蒸气丰富的地方
- 可能发生水凝结的地方
- 水很可能溅到



显示屏安装后首次通电时，因为



不要将组装好的 PCB 堆叠在一起。否则，可能会损坏树脂（例如，割伤，刮伤，碎屑，破裂，分层和变形），并且线材会断裂而导致灾难性故障（即 LED 不亮）。

(4) Other precautions, please refer to our "Ruifeng Photoelectric Full color SMD LED device User Manual".

其他注意事项,请参考我司《瑞丰光电全彩 SMD LED

4.1.7 Declare 申明

(1) This specification is written both in English and in Chinese and the latter is formal.

此规格书以中英文方式书写，若有冲突以中文版本为准。

(2) Both the customers and Refond will agree on official specifications of supplied products before

T Vhf ϕ Xef i b h Xcϕ Vh Vgba! G Xfc XVV Tgba f i T Wba TgXeUXf ZaXW4 aWEXb aW

reserves the right to further modify the specification for technical reference and sample without noticing the customers.

在量产供货前，瑞丰需与客户签署一份正式的产品规格书并各自备份。规格书签核后有效，对于作为技术参考以及送样时提供的规格书，瑞丰保留进一步修改而不需通知客户的权力。





www.refond.com



Declare 申明

This specification is written both in English and in Chinese and the latter is formal.

产品规格书以中英文方式书写，以中文方式为准。

